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** CONTINUING DATA *****

** FOREIGN APPLICATIONS *****

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35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	EXAMINER'S SIGNATURE <i>[Signature]</i> INITIALS <i>[Initials]</i>			
Verified and Acknowledged				

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TITLE

Via-filling material and process for fabricating semiconductor integrated circuit using the material

☐ All Fees☐ 1.16 Fees (Filing)☐ 1.17 Fees (Processing Fee of

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